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(54) SEMICONDUCTOR MODULE

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor module having a high joining strength, a high heat conducting property, and a long service life.

SOLUTION: In a semiconductor module, the occurrence of such a problem that, the joining strength between a chip mounting surface 5 and a heat radiating member 7, such as the heat sink, etc., is deteriorated by thermal stresses, is reduced as compared with the conventional example, because the substrate 5 is press-contacted with the member 7 in a finely displaceable state by using an elastic pressing member 12, and the substrate 5 and member 7 can freely expand and shrink even when a difference exists between the coefficients of thermal expansion of the substrate 5 and member 7. Since the substrate 5 is press-contacted with the member 7 through heat-conductive grease, in addition, a high heat radiating property can be secured.

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